

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS AND POLISHING METHOD

5 A polishing apparatus capable of polishing a substrate while accurately
measuring a temperature at a desired measuring point near a surface of the substrate is
disclosed. The polishing apparatus includes: a polishing pad having a polishing surface
for polishing a substrate; a polishing table supporting the polishing pad; a table motor
configured to rotate the polishing table; a polishing head configured to press a surface of
10 the substrate against the polishing surface of the polishing pad; a polishing liquid supply
nozzle configured to supply a polishing liquid onto the polishing surface of the polishing
pad; and a temperature sensor mounted to the polishing table. The temperature sensor is
located so as to move across the surface of the substrate each time the polishing table
makes one revolution.

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FIG. 1